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In the Claims:

Following is a complete listing of the claims pending in the application, as amended:

1-2. (Canceled)

3. (Currently Amended) ~~The planarizing machine of claim 1A~~ planarizing machine, comprising:

a table having a support surface;

a processing pad on the support surface;

a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head relative to the support surface; and

a solution dispenser separate from the head, the solution dispenser being configured to discharge a planarizing solution onto a plurality of locations on the pad, wherein the solution dispenser comprises: an elongated support extending over the pad at a location spaced apart from a travel path of the head; a fluid passageway carried by the support through which a planarizing solution can flow; and an elongated slot extending along at least a portion of the support, the slot being in fluid communication with the fluid passageway to create an elongated flow of planarizing solution.

4. (Currently Amended) ~~The planarizing machine of claim 1A~~ planarizing machine, comprising:

a table having a support surface;

a processing pad on the support surface;

a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head relative to the support surface; and

a solution dispenser separate from the head, the solution dispenser being configured to discharge a planarizing solution onto a plurality of locations on the pad.

wherein the solution dispenser comprises an elongated support ~~extending~~ over the pad at a location spaced apart from a travel path of the head, a channel along at least a portion of the support through which a planarizing solution can flow, and a lip along at least a portion of the channel over which the planarizing solution can flow.

5-13. (Canceled)

14. (Currently Amended) ~~The planarizing machine of claim 12-A planarizing machine, comprising:~~

a table having a support surface;
a processing pad on the support surface;
a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head; and
a solution dispenser separate from the head, the solution dispenser having a support over the pad and a distributor carried by the support, the distributor being configured to discharge a planarizing solution from a plurality of locations along the support, wherein the support comprises an elongated arm and a fluid passageway carried by the arm through which a planarizing solution can flow, and the distributor further comprises an elongated slot along at least a portion of the arm, the slot being in fluid communication with the fluid passageway to create an elongated flow of planarizing solution.

15. (Currently Amended) ~~The planarizing machine of claim 12-A planarizing machine, comprising:~~

a table having a support surface;
a processing pad on the support surface;
a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head; and
a solution dispenser separate from the head, the solution dispenser having a support over the pad and a distributor carried by the support, the distributor

being configured to discharge a planarizing solution from a plurality of locations along the support wherein: the support comprises an elongated arm and a channel along at least a portion of the arm through which a planarizing solution can flow; and the distributor further comprises a weir along at least a portion of the channel over which the planarizing solution can flow.

16-24. (Canceled)

25. (Original) A planarizing machine, comprising:
a table having a support surface;
a processing pad on the support surface;
a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head; and
a solution dispenser having an elongated opening along the fluid conduit through which a planarizing solution can flow.

26. (Original) A planarizing machine, comprising:
a table having a support surface;
a processing pad on the support surface;
a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head; and
a solution dispenser having an elongated weir over which a planarizing solution can flow.

27-31. (Canceled)

32. (Currently Amended) The method of claim 30-A method of processing a microelectronic workpiece, comprising:

removing material from the workpiece by pressing the workpiece against a contact surface of a processing pad and imparting relative motion between the workpiece and the contact surface;

depositing a first flow of a planarizing solution from a dispenser directly onto a first region of the contact surface; and

depositing a second flow of the planarizing solution from the dispenser directly onto a second region of the contact surface separate from the first region, wherein: the dispenser comprises a support, a first elongated slot along a first section of the support, and a second elongated slot along a second section of the support, and depositing the flow of the planarizing solution comprises discharging planarizing solution through the first and second slots at a common flow rate, the first slot discharging the first flow and the second slot discharging the second flow.

33-45. (Canceled)

46. (Currently Amended) The method of claim 43-A method of processing a microelectronic workpiece, comprising:

removing material from the workpiece by pressing the workpiece against a contact surface of a processing pad and imparting relative motion between the workpiece and the contact surface; and

discharging a planarizing solution directly onto a first region of the contact surface and concurrently discharging the planarizing solution directly onto a second region of the contact surface separate from the first region, the planarizing solution being deposited onto the first and second regions separate from a head carrying the workpiece, wherein: the planarizing solution is discharged through a dispenser having

a support and an elongated slot extending along at least a portion of the support; and discharging the planarizing solution onto the pad comprises passing a flow of planarizing solution through the slot.

47. (Currently Amended) The method of claim 43-A method of processing a microelectronic workpiece, comprising:

removing material from the workpiece by pressing the workpiece against a contact surface of a processing pad and imparting relative motion between the workpiece and the contact surface; and

discharging a planarizing solution directly onto a first region of the contact surface and concurrently discharging the planarizing solution directly onto a second region of the contact surface separate from the first region, the planarizing solution being deposited onto the first and second regions separate from a head carrying the workpiece wherein the planarizing solution is discharged through a dispenser having a support and an elongated weir extending along at least a portion of the support; and discharging the planarizing solution onto the pad comprises passing a flow of planarizing solution over the weir.

48-55. (Canceled)

56. (New) A planarizing machine, comprising:

a table having a support surface;

a processing pad on the support surface;

a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head relative to the support surface; and

a solution dispenser separate from the head, the solution dispenser including an elongated support over the pad, a fluid passageway carried by the support, and an elongated element along at least a portion of the support, the elongated element being in fluid communication with the fluid passageway and

configured to create a flow of planarizing solution elongated along a longitudinal dimension of the support.

57. (New) The planarizing machine of claim 56 wherein the elongated element comprises an elongated slot through which the planarizing solution can flow.

58. (New) The planarizing machine of claim 56 wherein the elongated element comprises a weir having an elongated lip over which the planarizing solution can flow.